

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|-----------------|---|-----------------|---------------|-------------------------|----------------|
| Die | Doped Silicon | Silicon (Si) | 7440-21-3 | 0.05 | 100.0 | 1 |
| | | | Subtotal | 0.05 | 100 | 1 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.47 | 100.0 | 9.36 |
| | Pure metal | Aluminium (Al) | 7429-90-5 | 0.01 | 100.0 | 0.13 |
| | | | Subtotal | 0.48 | 200 | 9.49 |
| Post-plating | Lead alloy | Tin (Sn) | 7440-31-5 | 1.36 | 100.0 | 27.2 |
| | | | Subtotal | 1.36 | 100 | 27.2 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0 | 0.03 | 0 |
| | Copper alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0 | 0.03 | 0 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0 | 0.1 | 0 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 0 | 99.84 | 0 |
| | | | Subtotal | 0 | 100 | 0 |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 6.25 | 6.5 | 125.36 |
| | Polymer | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2 | 15.37 | 16.0 | 308.58 |
| | Filler | Silica fused | 60676-86-0 | 68.22 | 71.0 | 1369.31 |
| | Flame retardant | Metal hydroxide | | 6.25 | 6.5 | 125.36 |
| | | | Subtotal | 96.09 | 100 | 1928.61 |
| Solder Wire | Lead alloy | Tin (Sn) | 7440-31-5 | 0.1 | 5.0 | 2 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.05 | 2.5 | 1 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 1.84 | 92.5 | 37 |
| | | | Subtotal | 1.99 | 100 | 40 |
| Die | Metal oxide | Lead Dioxide (PbO2) | 1309-60-0 | 0 | 0.98 | 0.01 |
| | Doped Silicon | Silicon (Si) | 7440-21-3 | 0.05 | 99.02 | 0.99 |
| | | | Subtotal | 0.05 | 100 | 1 |
| | | | Total | 100.02 | 100 | 2007.3 |

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